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# Characterization of ALD-grown aluminum oxide field insulators for silicon detectors

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# Target

Fabricate MCz-Si n-in-p pixel detectors without p-spray/p-stop implants using an oxide with negative charge as field insulator and dielectric

→ **replace  $\text{SiO}_2$  with  $\text{Al}_2\text{O}_3$**

Investigate effect of process parameters on the electrical properties of alumina

Compare results of corona charge characterization to conventional CV/IV

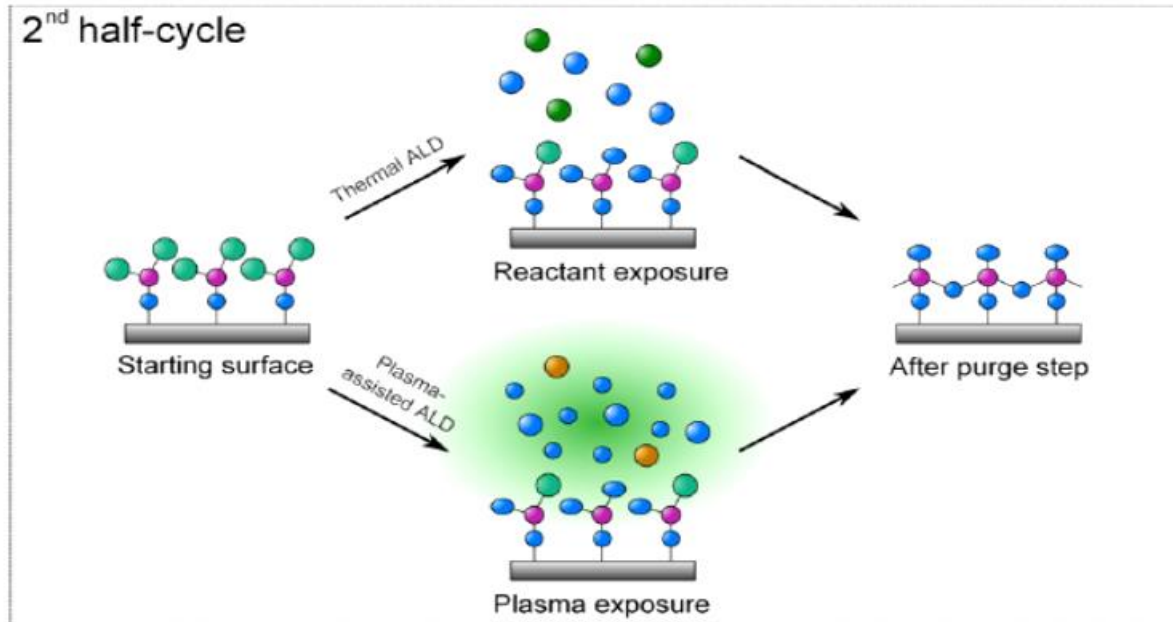
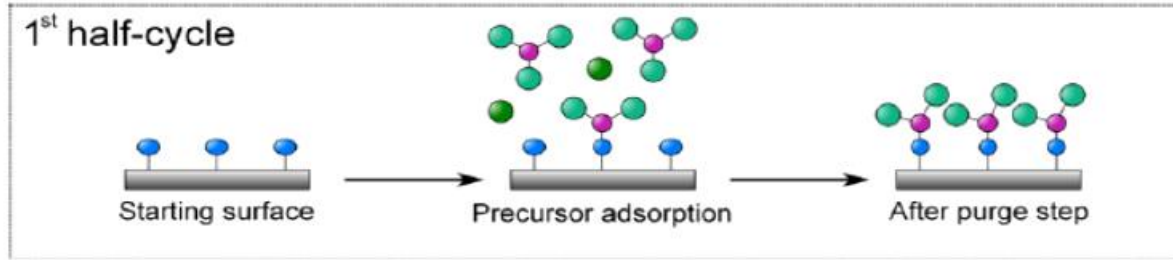
# Outline

- **Introductions to...**
  - ALD
  - COCOS
- **Thin film characterization results**
- **Device processing**
- **Diode and MOS capacitor characterization**
- **Summary**

# Atomic Layer Deposition

- A film is deposited by alternate pulsing of gaseous precursors over a substrate
- No gas-phase reactions, purges between the precursor pulses → self-limiting surface reactions
- High film uniformity over relatively large areas
- Film growth slow and occurring in cycles → very thin layers can be grown with good accuracy and repeatability

# Atomic Layer Deposition



# ALD of $\text{Al}_2\text{O}_3$

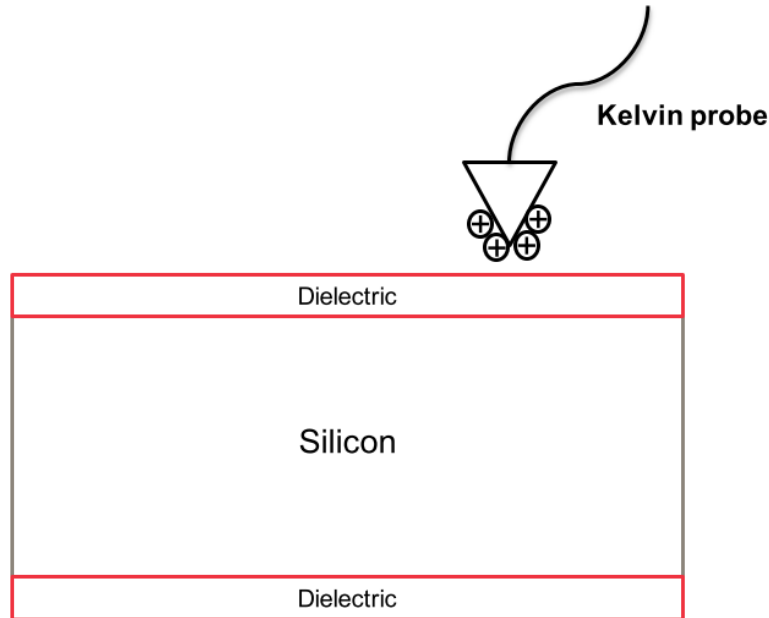
- **Trimethylaluminium (TMA) +  $\text{H}_2\text{O}$**
- **Two temperatures**
  - 200 C
  - 300 C
- For processing: 50 nm at 200 C, 70 nm at 300 C

# Corona oxide characterization of semiconductors (COCOS)

- **Corona charge is applied onto the oxide surface and the potential difference is measured - in the dark and under illumination**
- **Enables determination of dielectric properties from unprocessed thin films**

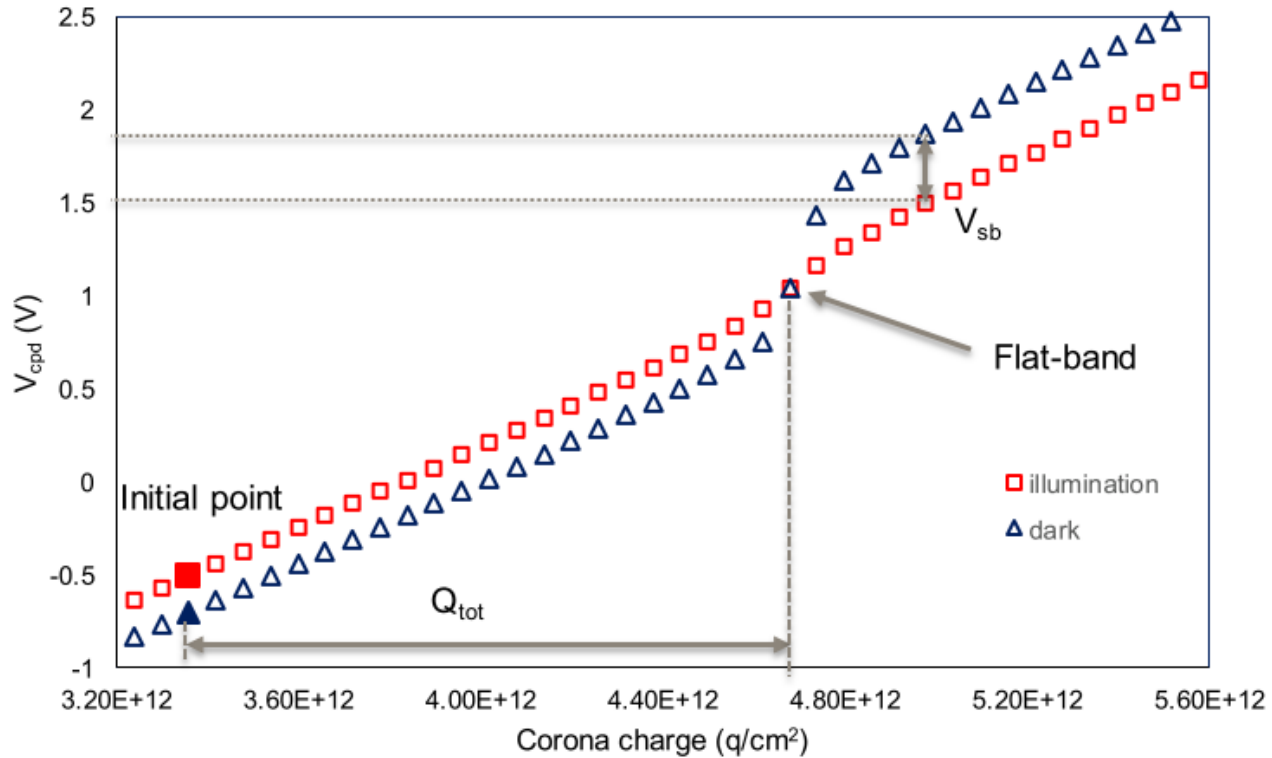
# Corona oxide characterization of semiconductors (COCOS)

- Main parameters to be extracted:  $K_{ox}$ ,  $V_{fb}$ , total oxide charge  $Q_{tot}$ , interface defect density  $D_{it}$
- For p-type substrate: sweep from accumulation to depletion and inversion





# Corona oxide characterization of semiconductors (COCOS)

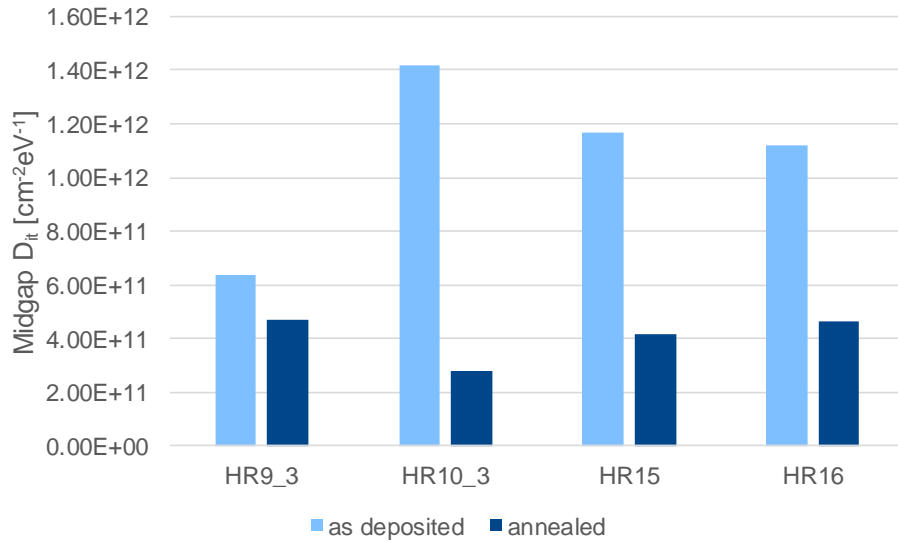


# Characterization and results

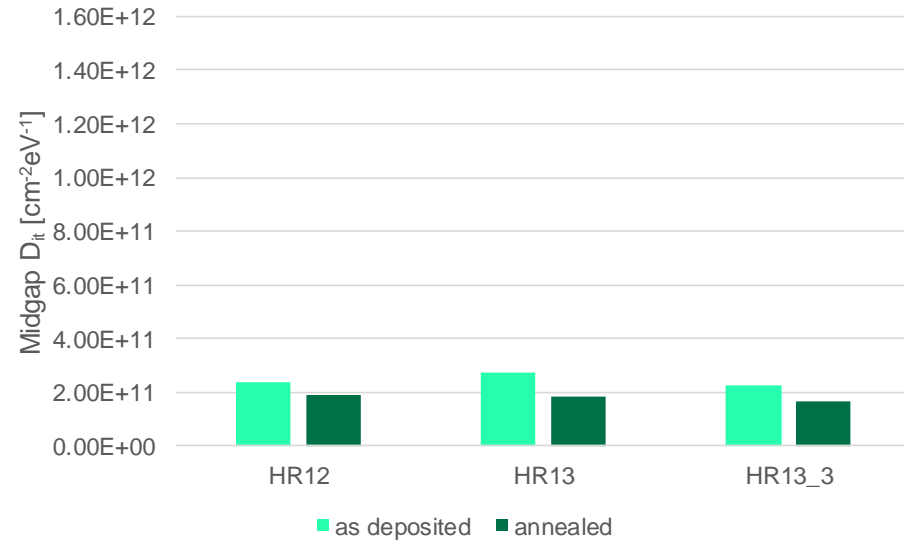
- **Thin films:**
  - **Pre- vs post-anneal**
  - **200 C vs 300 C**
  - $D_{it}$ ,  $Q_{tot}$ ,  $V_{fb}$
  - (Effective charge carrier lifetimes)
- **Processed structures:**
  - **Diodes and MOS capacitors**
  - CV
  - IV

# COCOS – $D_{it}$

## 200 C

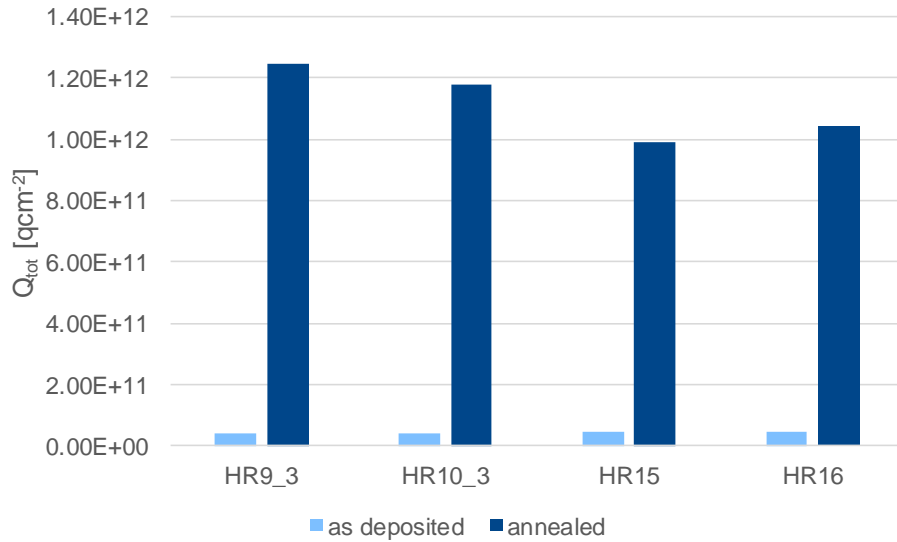


## 300 C

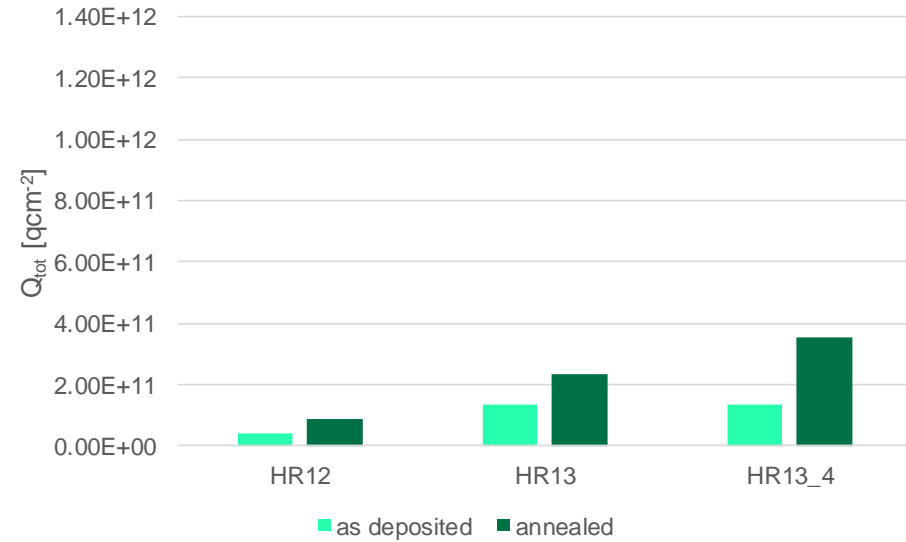


# COCOS – $Q_{tot}$

## 200 C

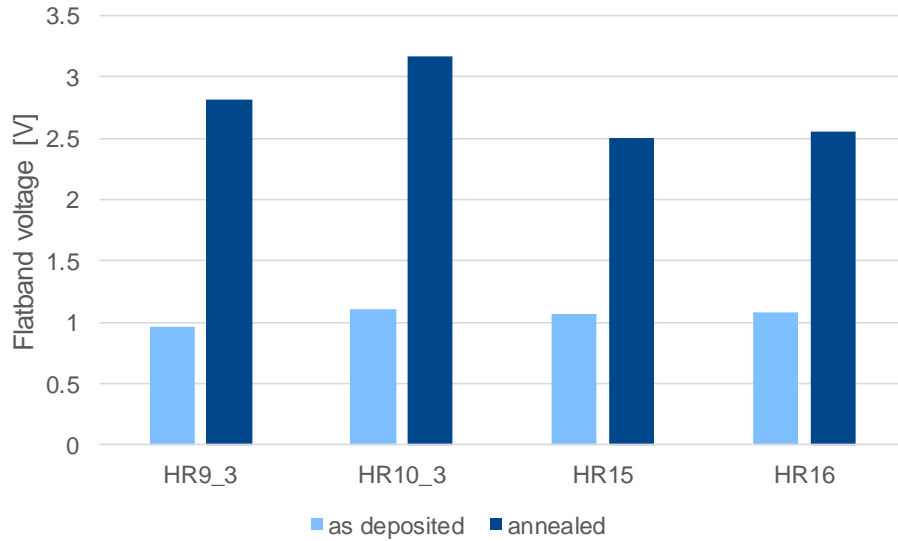


## 300 C



# COCOS – $V_{fb}$

## 200 C



## 300 C



# Characterization and results

- Thin films:
  - Pre- vs post-anneal
  - $Q_{\text{tot}}$ ,  $D_{\text{it}}$ ,  $V_{\text{fb}}$
  - (Effective charge carrier lifetimes)
- **Processed structures:**
  - **Diodes and MOS capacitors**
  - CV
  - IV

# Processing

High-res p-type 6" Si wafer



Implantation:  
front side P, back side B



Activation



ALD  $\text{Al}_2\text{O}_3$

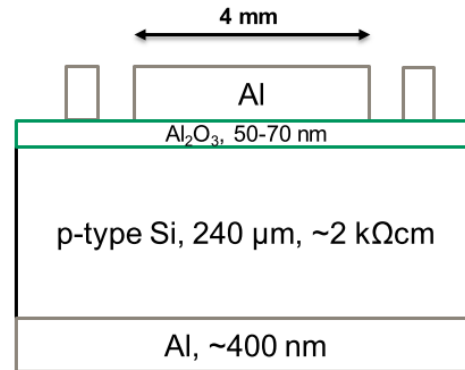


Al metallization

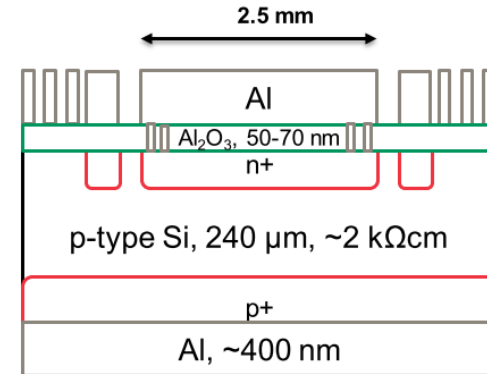


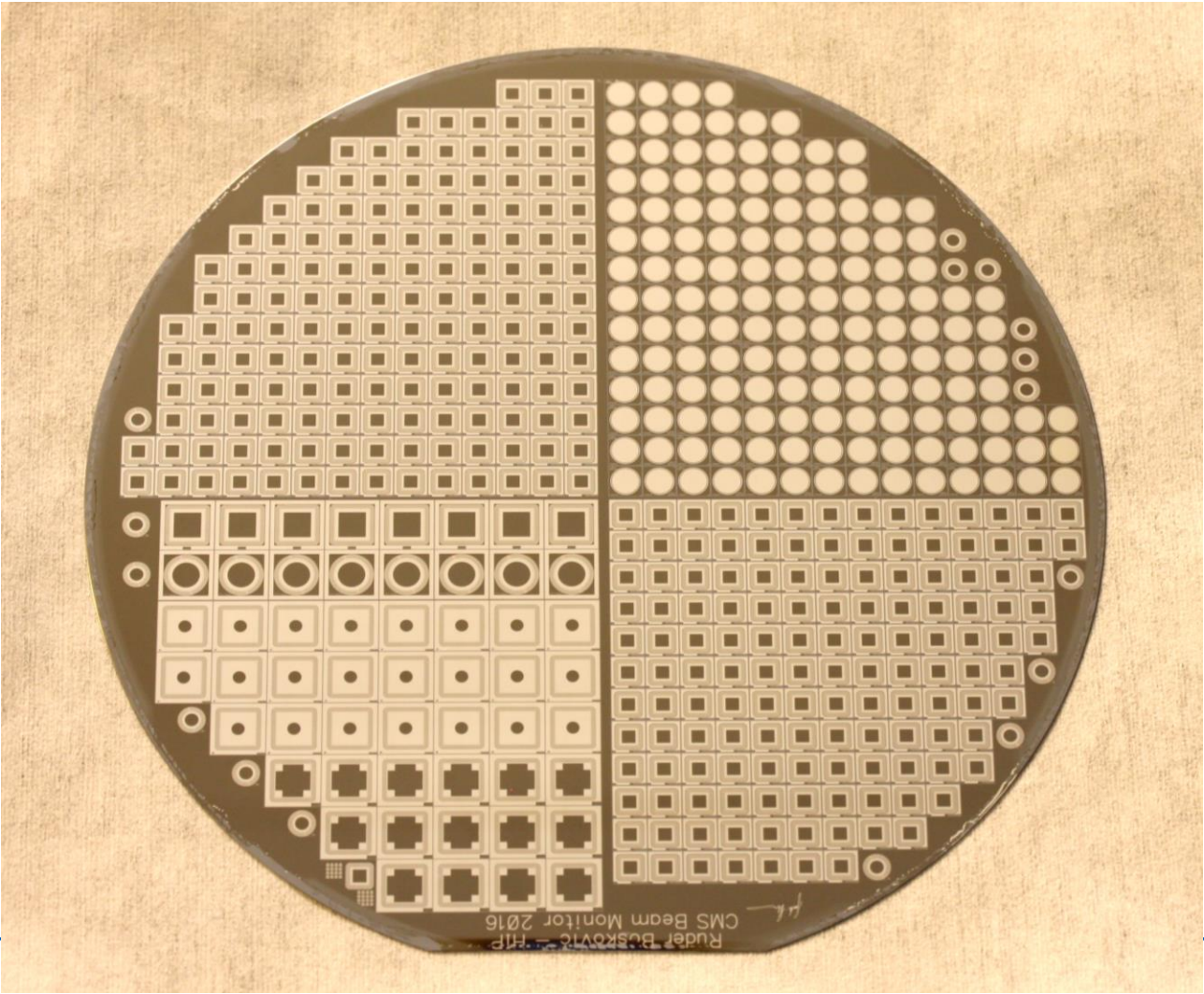
Sintering

## MOS capacitor



## Square diode



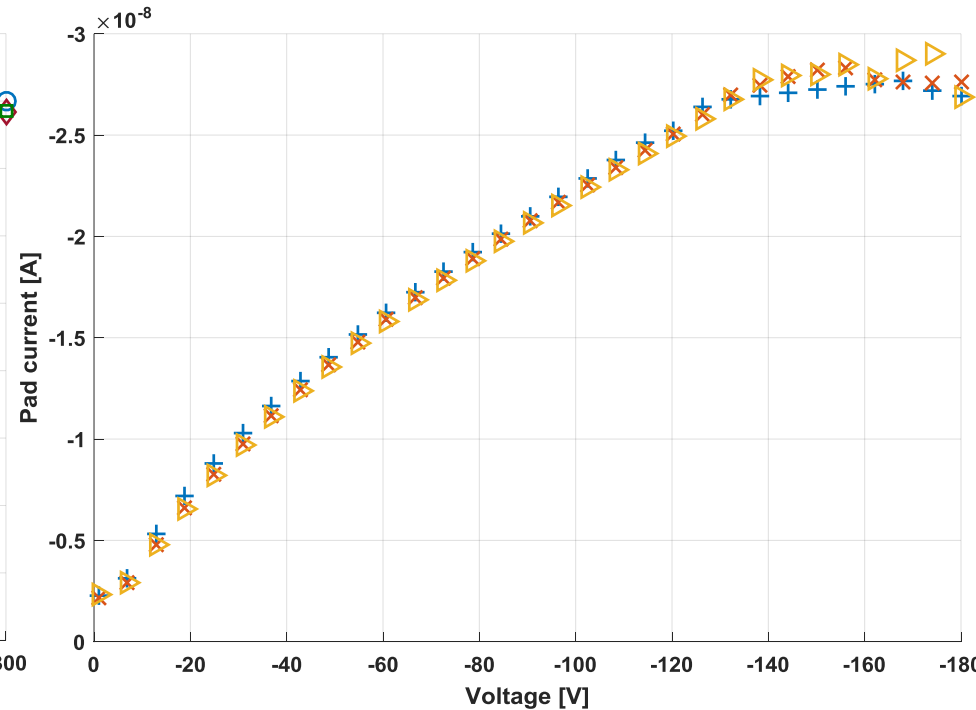
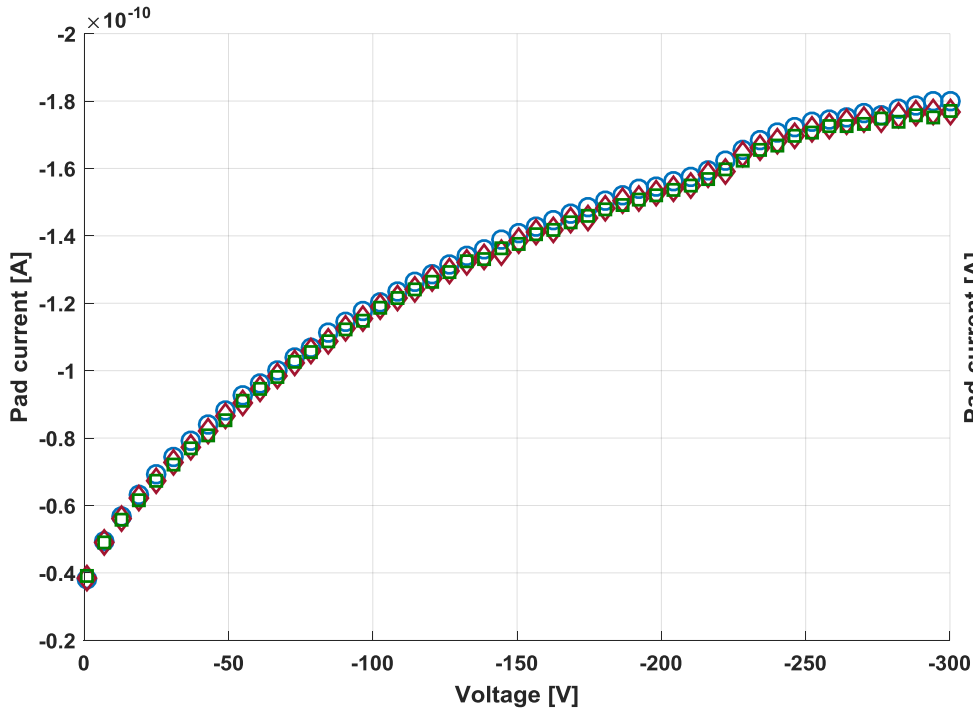




# Diodes – IV pad current

200 C

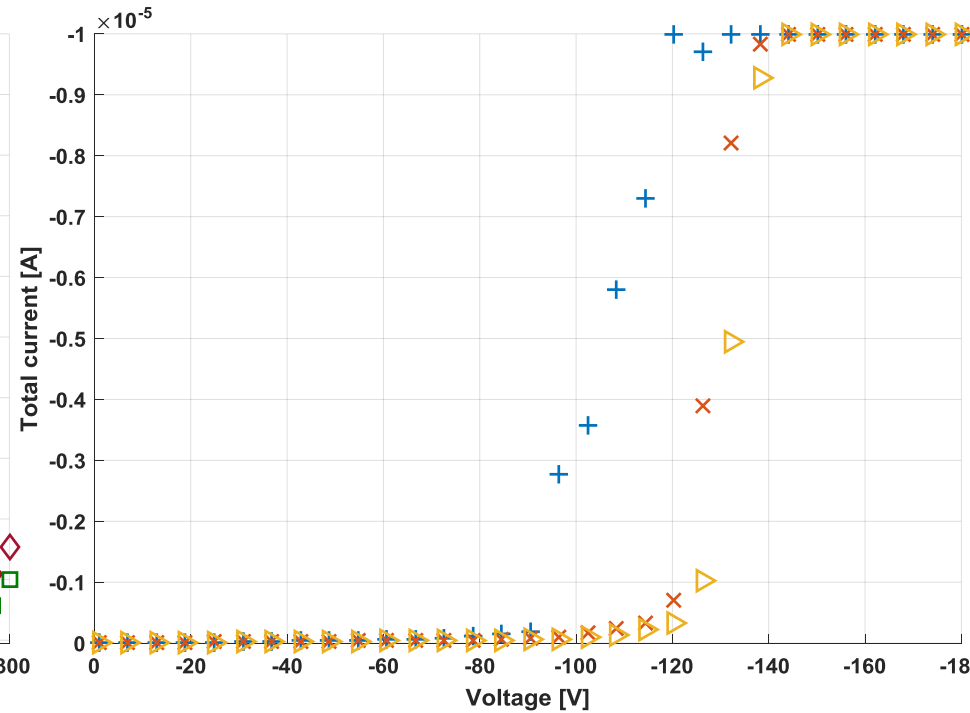
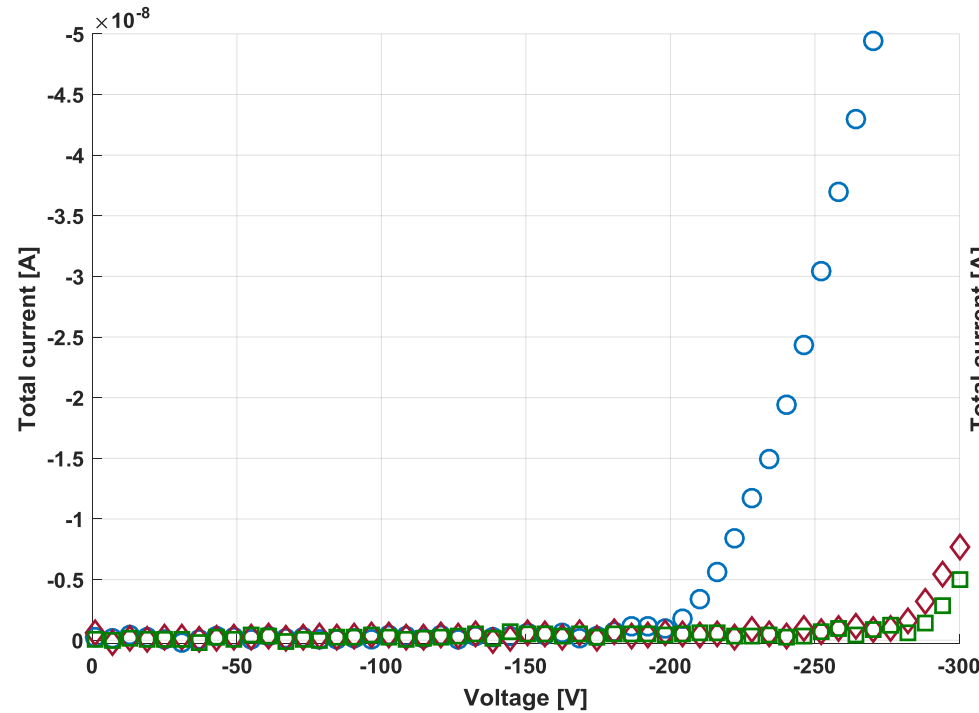
300 C



# Diodes – IV total current

200 C

300 C



# Diodes – IV

- **Measured up to -300 V at RT**

→ **Very clear difference between film deposition temperatures: films deposited at 300 C are inferior to those deposited at 200 C**

→ **”Creep” in total currents: breakdown shifts to higher voltages in consecutive measurements – potentially due to oxide trapped or interface charges that move at high bias?**

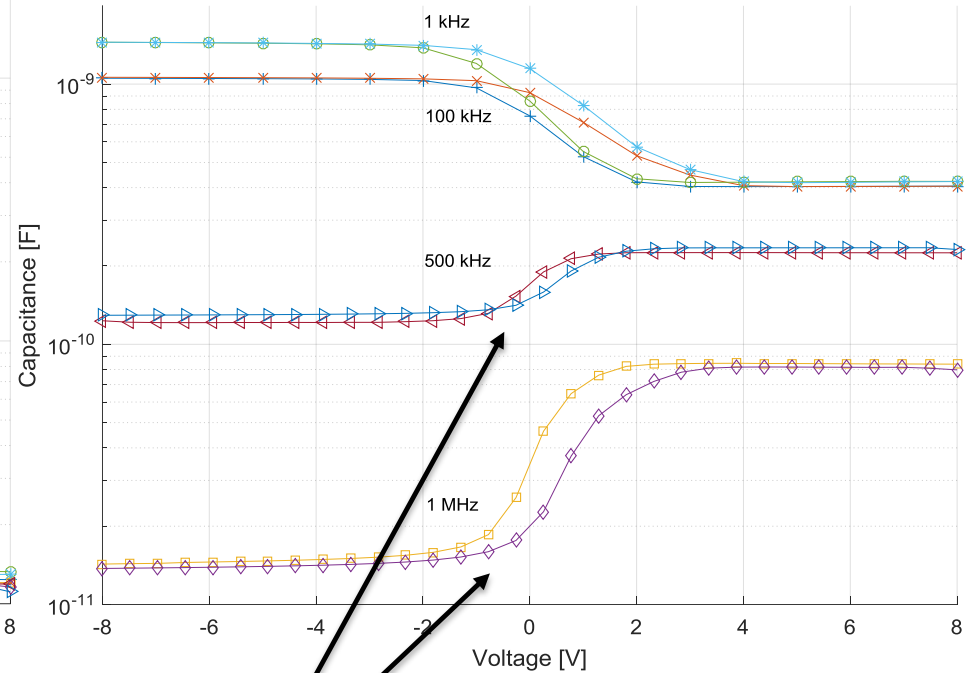
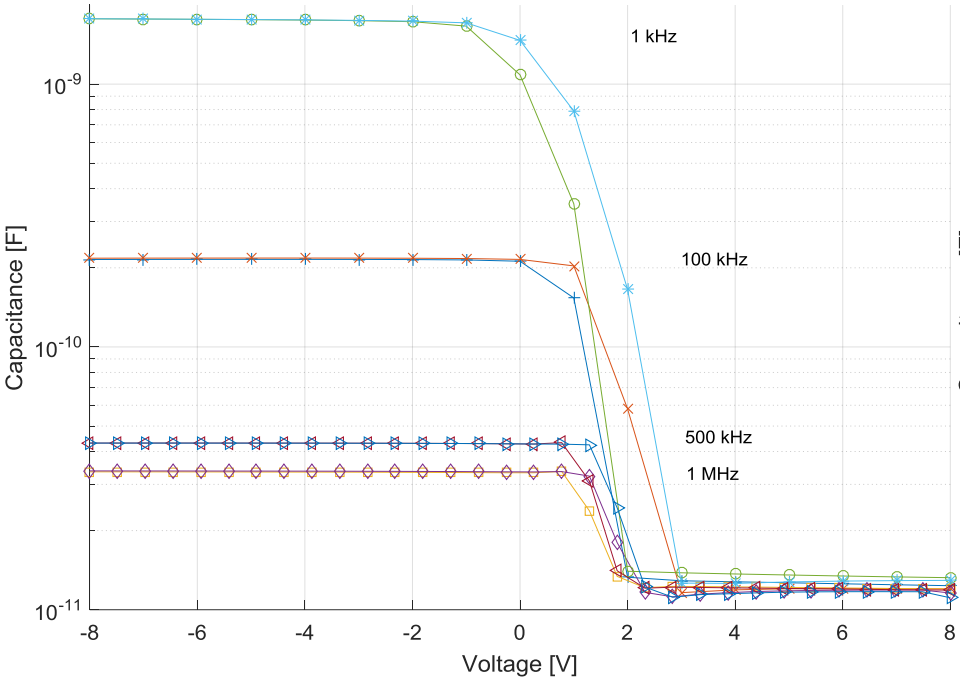
# MOS capacitors – CV

- **Frequencies 1 kHz, 100 kHz, 500 kHz, 1 MHz**
- **CV very stable over consecutive measurements**
- **Again clear difference for films grown at 200 C and 300 C**
- **Hysteresis visible for both film types – another sign of trapped charges?**
- **CV behavior frequency-dependent – again differences for different temperatures**

# MOS capacitors – CV frequency scan

200 C

300 C



# Contact CV vs COCOS

- $D_{it}$ : conventional CV curve contradictory to COCOS? Stretched-out curve interpreted as presence of interface traps/charge, but COCOS indicates lower  $D_{it}$  for 300 C films...
- $Q_{tot}$ : appears to correlate with performance in devices in the expected way – film with higher negative charge works better
- $V_{fb}$ : cannot be compared directly due to the introduction of the metal contact in processing

# Summary

- **Electrical properties of  $\text{Al}_2\text{O}_3$  thin films were characterized**
  - from pure thin films using the COCOS technique
  - from diode and MOS capacitor structures using conventional CV/IV measurements
- **$\text{Al}_2\text{O}_3$  grown at 200 C works reasonably well in diodes**
- **Differences in properties of films grown at 200 C and 300 C**
- **COCOS  $V_{fb}$  and  $Q_{tot}$  appear to correlate with film performance in diodes – lifetime is not a sufficient indicator**
- **Interesting effects in MOS capacitor CV – need to be understood better**

# Plans for the near future

- Investigate the use of ozone or O plasma in ALD of alumina, try Ti doping of oxide
- Reproduce results for different substrates
- Irradiation studies:
  - High gamma and X-ray doses
  - TCT and DLTS pre- and post-irradiation

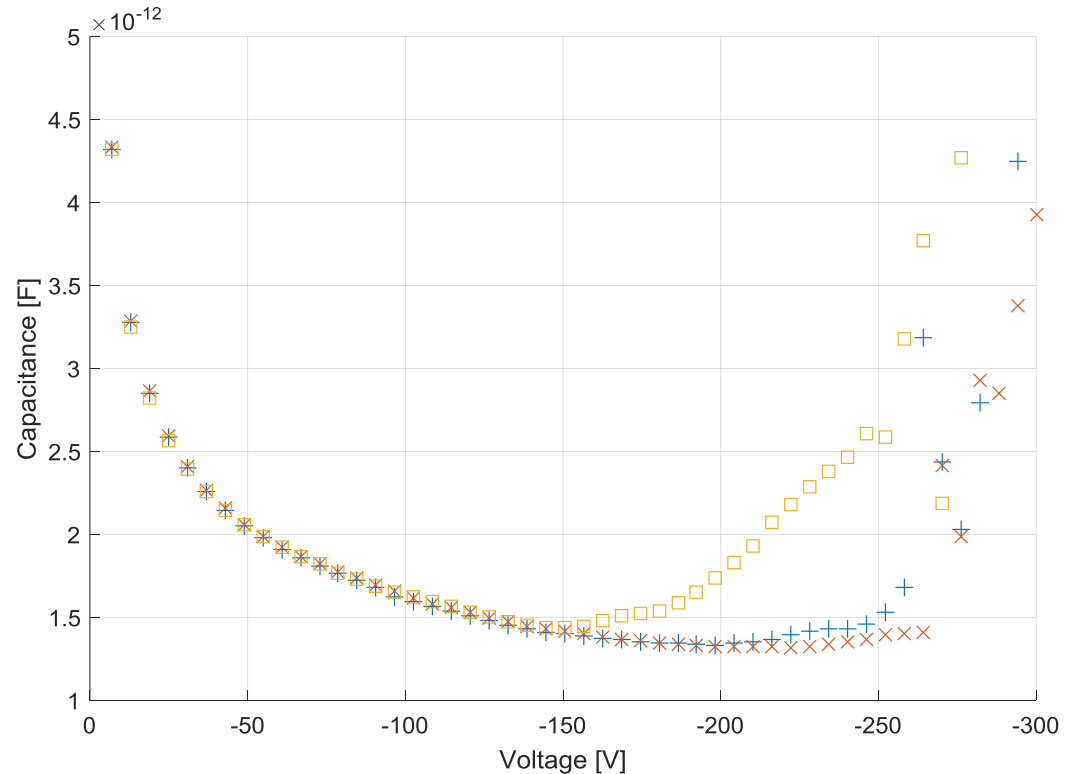


# Thank you for your attention!

# Backup

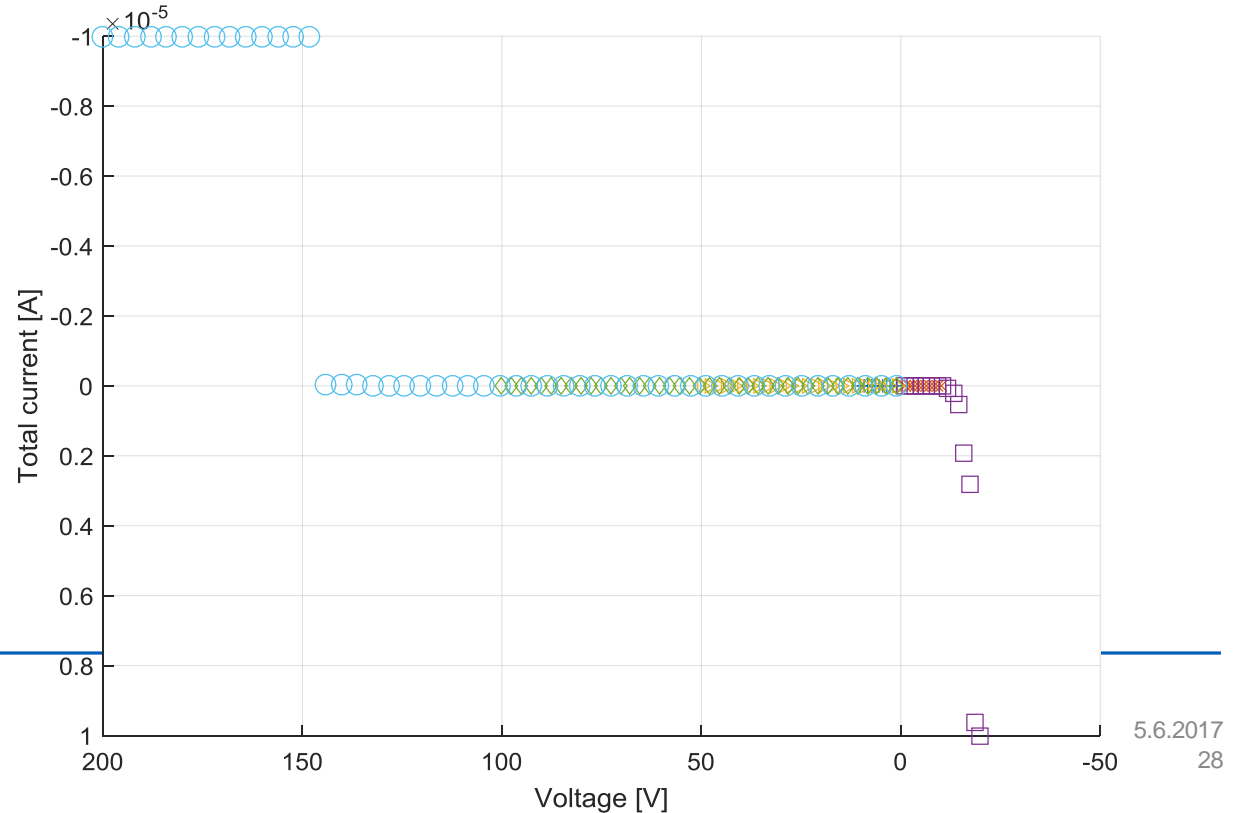
# Diodes – CV

- Depletion voltage around 200 V – rather high, is due to high resistivity p-type substrate
- ”Creep” visible



# MOS capacitors - IV

- ... In order to see dielectric breakdown
- IV is not identical in different polarities
- due to destructive measurement?



# Motivation

- **Vast amount of silicon detectors in high-energy physics experiments with high radiation doses**
  - **n-type Si replaced with p-type, Fz with Cz silicon**
    - n-in-p detectors
    - Process temperatures  $< 400\text{ C}$
    - Passivation and isolation of segments with  $\text{SiO}_2$  not possible without extra implants
- **Solution – using an oxide with negative charge, e.g.  $\text{Al}_2\text{O}_3$  ?**